

87654321

UNLESS OTHERWISE SPECIFIED. ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.

2. HOLE SIZE APPLIES AFTER PLATING. TOLERANCE TO BE +/- .003.
VIA HOLE SIZES 8,10,15 AND 12MILS APPLY AFTER PLATING. TOLERANCE TO BE +.003/- .010.

3. REGISTRATION TOLERANCE: ARTWORK +/- .002
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.

4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.

5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER, USE VIASYSTEMS STACKUP "DAC38J84_R04350". DETAIL "A" IS FOR REFERENCE.
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: 0.062 +/-10%

6. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.

7. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT).
COLOR=RED (0.001 TO 0.002" THICK OVER METAL). VIASYSTEMS STACKUP JOB NAME: DAC38J84_R04350

8. SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.

9. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.

10. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH.
MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.

11. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

12. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

13. OUTER LAYERS USING A 20mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/- 10% TOLERANCE.
OUTER LAYERS USING A 9.5mil TRACE WIDTH AND 5.5mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 10% TOLERANCE.

14. MINIMUM COPPER CONDUCTOR WIDTH IS: 6MIL
MINIMUM COPPER SPACING IS: 4 MIL.

15. SURFACE FINISH TO BE 3-8 uIN GOLD OVER 100-200 uIN NICKEL PLATING.

16. GROUND ETCH TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.

17. NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.

18. FINISHED BOARD MUST BE RoHS COMPLIANT AND SURVIVE A LEAD FREE ASSEMBLY,
MAXIMUM REFLOW OF 260 DEGREES C (6 PASSES).

19. ALL 8,10,12 & 15mil DRILLS NEED TO BE PLATED OVER TO HAVE FILL AND FLAT FINISH ON BOTH SIDES.

REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED
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DETAIL "A"

VIASYSTEMS STACKUP JOB NAME: DAC38J84_R04350
THIS STACK UP DETAIL IS FOR REFERENCE ONLY

LAYER 1

TOP

Copper Foil 0.25oz / Plate to 0.5oz min Layer 1

R4350B

Pre-preg 0.010"

LAYER 2

370HR

Core 0.0058" 1oz / 1oz Layer 2 & 3

LAYER 3

370HR

Pre-preg 0.0060"

LAYER 4

370HR

Core 0.0058" 1oz / 1oz Layer 4 & 5

LAYER 5

370HR

Pre-preg 0.0060"

LAYER 6

370HR

Core 0.0058" 1oz / 1oz Layer 6 & 7

LAYER 7

R4350B

Pre-preg 0.010"

LAYER 8

BOTTOM

Copper Foil 0.25oz / Plate to 0.5oz min Layer 8

2.626

1.968

0.795

0.795

0.616

2.500

4.475

1.275

4.120

2.680

6.800

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
•	8.0	PLATED	645
•	10.0	PLATED	1825
•	10.0	PLATED	44
•	12.0	PLATED	884
•	15.0	PLATED	8
•	38.0	PLATED	20
•	40.0	PLATED	7
◦	62.0	PLATED	14
◦	67.0	PLATED	4
◻	106.0	PLATED	2
○	120.0	PLATED	2
A	125.0	PLATED	6
B	140.0	PLATED	1
◁	39.0	NON-PLATED	2
▷	50.0	NON-PLATED	2
E	125.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
+/- .XX +/- .01 +/-
.XXX +/- .005 +/-

CONTRACT NO.

APPROVALS

DATE

DRAWN KIM LE 09/03/2014

ENGR M GUIBORD 09/03/2014

MATERIAL

SEE NOTE 5

FINISH

SEE NOTES 7, 8, 9

DO NOT SCALE DRAWING

TEXAS INSTRUMENTS INC.

FABRICATION DRAWING
ADS54J66, ADS58J63, ADS58J66

SIZE B

CODE

IDENT NO.

DRAWING NO.

REV. A

SCALE NONE

SHEET 1 OF 1